IPC ASSOCIATION ELECTRONIC	Material Com © Copyright 2005, international and P	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under be international and Pan-American copyright conventions.		nder both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Mater					ials and Mfg Information			
upplier	r Information														
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi											2024-05-01				
ontact N	ame	Title - Contact			F	Phone - Contact*					Email - Contact*				
Product-I	Env-Stewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com				
uthorize	d Representative*	Title - Representative			F	Phone - Representative*				Email - Representative*					
roduct-I	Env-Stewards	Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	n	Manufacturing Site		W	eight*	UOM	Unit Type
	2SB1203S-E		BS-E	BIP PNP 5A 50V			2024-05-01			CNG		32	6.57	mg	Each
lanufa	cturing Process Inform		Cerminal Base	Alloy	-STD-020 MS	I Pating	Peak Proc	ese Rody '	Temperatu	re May Ti	me at Peak	Temperatur	e Numb	er of Reflow Cyc	
	ů í		CU Alloy NA			L Katilig	Peak Process Body Temperature N		1			er of Kerlow Cyc	cies		
omments			Alloy	1	113		U			130		Seconds	13		
Jiiiiiciits	,														
r more i	information regarding materi	al composition	nlesse refer t	n nage 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Itability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	es per the definition above except for selected exemp	otions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		'Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-6_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.04	mg	Supplier	Silicon (Si)	7440-21-3		1.04	mg
Die Attach Solder	0.49	mg	Supplier	Silver (Ag)	7440-22-4		0.0123	mg
			A	Lead (Pb)	7439-92-1	7a	0.4533	mg
			Supplier	Tin (Sn)	7440-31-5		0.0245	mg
Lead Frame	191.37	mg	Supplier	Silver (Ag)	7440-22-4		0.3827	mg
			Supplier	Tin (Sn)	7440-31-5		0.2679	mg
			Supplier	Copper (Cu)	7440-50-8		190.7193	mg
Mold Compound-Black	129.7	mg		Brominated epoxy resin	proprietary data		1.8158	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		5.8365	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		1.1673	mg
			Supplier	Carbon Black (C)	1333-86-4		1.297	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		97.275	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		22.049	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.2594	mg
Plating	3.34	mg	В	Bismuth (Bi)	7440-69-9		0.02	mg
			Supplier	Tin (Sn)	7440-31-5		3.32	mg
Wire Bond - Au	0.63	mg	Supplier	Gold (Au)	7440-57-5		0.63	mg